

**Date:** July 2019  
**Rev:** IX  
**No. of Components:** Single  
**Mix Ratio by Weight:** N/A  
**Specific Gravity:** 2.00  
**Pot Life:** 28 Days  
**Shelf Life- Bulk:** One year at -40°C  
**Shelf Life- Syringe:** Six months at -40°C

**Recommended Cure:** 150°C / 1 Hour

**NOTES:**

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Complies with the requirements of MIL-STD 883/Method 5011.

**Product Description:** EPO-TEK® H67-MP is a single component, thermally conductive epoxy for hybrid die and component attach. It can also be used for semiconductor and high temperature ceramic and vacuum packaging.

**Typical Properties:** Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	White		
* Consistency:	Highly viscous paste		
* Viscosity (23°C) @ 1 rpm:	300,000-400,000	cPs	
Thixotropic Index:	N/A		
* Glass Transition Temp:	≥ 90	°C (Dynamic Cure: 20-300°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	16	x 10 <sup>-6</sup> in/in°C
	Above Tg:	68	x 10 <sup>-6</sup> in/in°C
Shore D Hardness:	84		
Lap Shear @ 23°C:	1,522	psi	
* Die Shear @ 23°C:	≥ 20	Kg	7,112 psi
Degradation Temp:	350	°C	
Weight Loss:			
	* @ 200°C:	0.48	%
	@ 250°C:	0.71	%
	@ 300°C:	1.22	%
Suggested Operating Temperature:	< 300 °C (Intermittent)		
Storage Modulus:	641,860	psi	
* Ion Content:	Cl <sup>-</sup> :	< 200 ppm	Na <sup>+</sup> : < 50 ppm
	NH <sub>4</sub> <sup>+</sup> :	87 ppm	K <sup>+</sup> : < 50 ppm
* Particle Size:	≤ 20 microns		

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	0.5	W/mK
Volume Resistivity @ 23°C:	≥ 6 x 10 <sup>13</sup>	Ohm-cm
Dielectric Constant (1KHz):	4.92	
Dissipation Factor (1KHz):	0.004	

Epoxyes and Adhesives for Demanding Applications™

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

EPOXY TECHNOLOGY, INC.

14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782

[www.epotek.com](http://www.epotek.com)

**EPO-TEK® H67-MP Advantages & Suggested Application Notes:**

- A very high viscosity and thixotropic paste suitable for screen printing or manual hand operations.
- Performs exceptionally well as a die-attach for small chips such as GaAs, LEDs and diodes, as well as SMDs.
- Capable of resisting 260°C green reflow process, low outgassing in hermetic lid-seal processes near 300°C, and organic burn-in up to 150°C/1000 hours storage.
- Complies with the requirements of MIL-STD 883/Method 5011. Yields low levels of water extractable ions such as chlorides.
- Capable of JEDEC Level II die-attach packaging on die-paddles and lead-frames.
- Widely used epoxy; popular choice for non-silver-filled die-attach epoxies; opto-packaging, hybrids, and many types of substrates including kovar, ceramic and BT.
- Available in different viscosity ranges – contact Technical Services at [techserv@epotek.com](mailto:techserv@epotek.com) for best recommendation.
- Can be used as nonconductive staking epoxy, in conjunction with EPO-TEK® H37-MP for attaching SMDs to hybrid circuits.
- A lower temp cure alternative to EPO-TEK® H65-175MP.

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